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DELPHI TECHNOLOGIES, INC.  
Legal Staff Mail Code CT10C  
P.O. Box 9005  
Kokomo, Indiana 46904-9005

3/15/02



Box Patent Applications  
Assistant Commissioner for Patents  
Washington DC 20231

Enclosed for filing are the following patent application papers:

Docket No. : DP-305031

Inventor(s) : Shing Yeh  
Bradley H. Carter  
Curtis W. Melcher


Title : LEAD-FREE SOLDER ALLOY AND SOLDER REFLOW PROCESS

Address all correspondence to:

JIMMY L. FUNKE  
DELPHI TECHNOLOGIES, INC.  
Legal Staff Mail Code CT10C  
P.O. Box 9005  
Kokomo, Indiana 46904-9005

Telephone : (248) 267-5554

Very Truly Yours,

  
JIMMY L. FUNKE  
Reg. No. 34166

Enclosures

I hereby certify that this document is being deposited with the United States Postal Service with sufficient postage as Express Mail addressed to Box Missing Parts, Assistant Commissioner for Patents, Washington, D.C. 20231 on March 15, 2002. Express Mail Label EK877647791US

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J10099861-031502